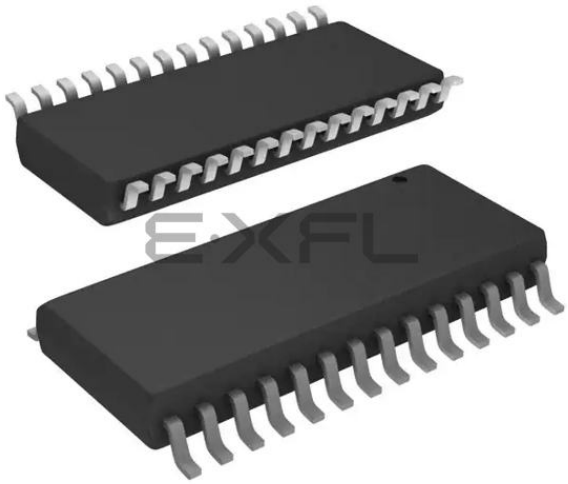

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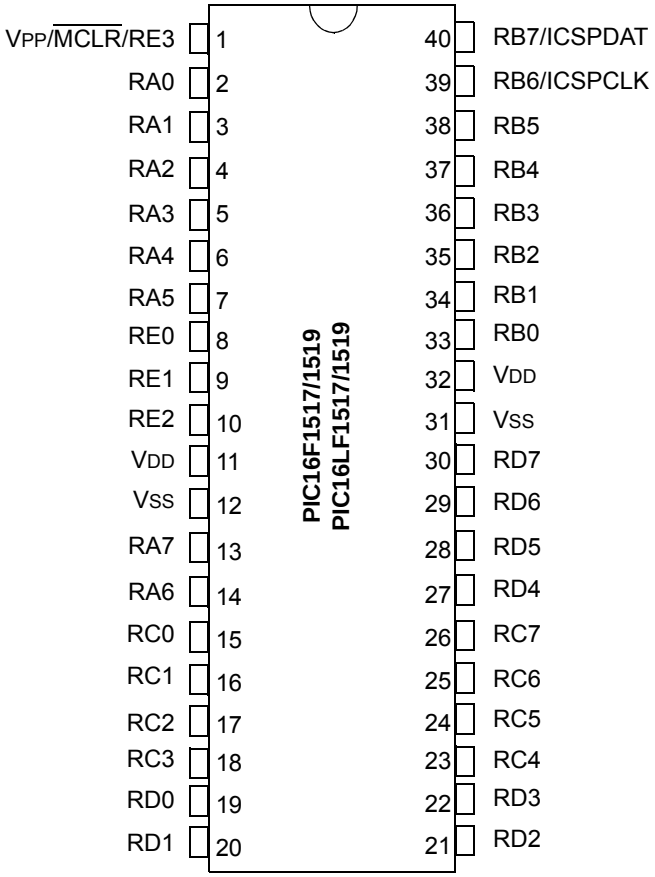
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	25
Program Memory Size	28KB (16K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 17x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf1518-e-so

FIGURE 4: 40-PIN PDIP PACKAGE DIAGRAM FOR PIC16(L)F1517/1519

40-Pin PDIP



Note 1: See Table 1 for location of all peripheral functions.

TABLE 3-3: PIC16(L)F1516/7 MEMORY MAP (CONTINUED)

Bank 31	
F80h	Core Registers (Table 3-2)
F8Bh	
F8Ch	Unimplemented Read as '0'
FE3h	
FE4h	STATUS_SHAD
FE5h	WREG_SHAD
FE6h	BSR_SHAD
FE7h	PCLATH_SHAD
FE8h	FSR0L_SHAD
FE9h	FSR0H_SHAD
FEAh	FSR1L_SHAD
FEBh	FSR1H_SHAD
FECh	—
FEDh	STKPTR
FEEh	TOSL
FEFh	TOSH
FF0h	Common RAM (Accesses 70h – 7Fh)
FFFh	

= Unimplemented data memory locations, read as '0',

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REGISTER 4-2: CONFIG2: CONFIGURATION WORD 2

R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	U-1
LVP	$\overline{\text{DEBUG}}$	$\overline{\text{LPBOR}}$	BORV	STVREN	—
bit 13					bit 8

U-1	U-1	U-1	R/P-1	U-1	U-1	R/P-1	R/P-1
—	—	—	$\overline{\text{VCAPEN}}$(1)	—	—	WRT<1:0>	
bit 7							bit 0

Legend:		
R = Readable bit	P = Programmable bit	U = Unimplemented bit, read as '1'
'0' = Bit is cleared	'1' = Bit is set	-n = Value when blank or after Bulk Erase

bit 13 **LVP:** Low-Voltage Programming Enable bit
1 = Low-voltage programming enabled
0 = High-voltage on MCLR must be used for programming

bit 12 **$\overline{\text{DEBUG}}$:** In-Circuit Debugger Mode bit
1 = In-Circuit Debugger disabled, ICSPCLK and ICSPDAT are general purpose I/O pins
0 = In-Circuit Debugger enabled, ICSPCLK and ICSPDAT are dedicated to the debugger

bit 11 **$\overline{\text{LPBOR}}$:** Low-Power BOR
1 = Low-Power BOR is disabled
0 = Low-Power BOR is enabled

bit 10 **BORV:** Brown-out Reset Voltage Selection bit(2)
1 = Brown-out Reset voltage (Vbor), low trip point selected.
0 = Brown-out Reset voltage (Vbor), high trip point selected.

bit 9 **STVREN:** Stack Overflow/Underflow Reset Enable bit
1 = Stack Overflow or Underflow will cause a Reset
0 = Stack Overflow or Underflow will not cause a Reset

bit 8-5 **Unimplemented:** Read as '1'

bit 4 **$\overline{\text{VCAPEN}}$:** Voltage Regulator Capacitor Enable bits(1)
If PIC16LF1516/7/8/9 (regulator disabled):
These bits are ignored. All VCAP pin functions are disabled.
If PIC16F1516/7/8/9 (regulator enabled):
0 = VCAP functionality is enabled on RA5
1 = All VCAP pin functions are disabled

bit 3-2 **Unimplemented:** Read as '1'

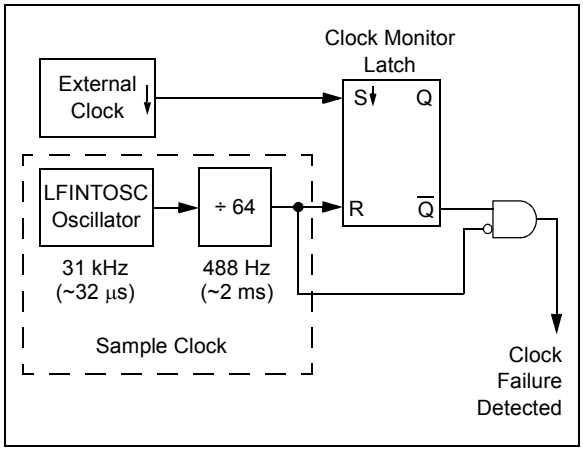
bit 1-0 **WRT<1:0>:** Flash Memory Self-Write Protection bits
8 kW Flash memory (PIC16(L)F1516/7 only):
11 = Write protection off
10 = 000h to 1FFh write-protected, 200h to 1FFFh may be modified by PMCON control
01 = 000h to FFFh write-protected, 1000h to 1FFFh may be modified by PMCON control
00 = 000h to 1FFFh write-protected, no addresses may be modified by PMCON control
16 kW Flash memory (PIC16(L)F1518/9 only):
11 = Write protection off
10 = 000h to 1FFh write-protected, 200h to 3FFFh may be modified by PMCON control
01 = 000h to 1FFFh write-protected, 2000h to 3FFFh may be modified by PMCON control
00 = 000h to 3FFFh write-protected, no addresses may be modified by PMCON control

Note 1: PIC16F1516/7/8/9 only.
2: See Vbor parameter for specific trip point voltages.

5.5 Fail-Safe Clock Monitor

The Fail-Safe Clock Monitor (FSCM) allows the device to continue operating should the external oscillator fail. The FSCM can detect oscillator failure any time after the Oscillator Start-up Timer (OST) has expired. The FSCM is enabled by setting the FCMEN bit in the Configuration Words. The FSCM is applicable to all external Oscillator modes (LP, XT, HS, EC, RC and secondary oscillator).

FIGURE 5-9: FSCM BLOCK DIAGRAM



5.5.1 FAIL-SAFE DETECTION

The FSCM module detects a failed oscillator by comparing the external oscillator to the FSCM sample clock. The sample clock is generated by dividing the LFINTOSC by 64 (see Figure 5-9). Inside the fail detector block is a latch. The external clock sets the latch on each falling edge of the external clock. The sample clock clears the latch on each rising edge of the sample clock. A failure is detected when an entire half-cycle of the sample clock elapses before the external clock goes low.

5.5.2 FAIL-SAFE OPERATION

When the external clock fails, the FSCM switches the device clock to an internal clock source and sets the bit flag OSFIF of the PIR2 register. Setting this flag will generate an interrupt if the OSFIE bit of the PIE2 register is also set. The device firmware can then take steps to mitigate the problems that may arise from a failed clock. The system clock will continue to be sourced from the internal clock source until the device firmware successfully restarts the external oscillator and switches back to external operation.

The internal clock source chosen by the FSCM is determined by the IRCF<3:0> bits of the OSCCON register. This allows the internal oscillator to be configured before a failure occurs.

5.5.3 FAIL-SAFE CONDITION CLEARING

The Fail-Safe condition is cleared after a Reset, executing a SLEEP instruction or changing the SCS bits of the OSCCON register. When the SCS bits are changed, the OST is restarted. While the OST is running, the device continues to operate from the INTOSC selected in OSCCON. When the OST times out, the Fail-Safe condition is cleared after successfully switching to the external clock source. The OSFIF bit should be cleared prior to switching to the external clock source. If the Fail-Safe condition still exists, the OSFIF flag will again become set by hardware.

5.5.4 RESET OR WAKE-UP FROM SLEEP

The FSCM is designed to detect an oscillator failure after the Oscillator Start-up Timer (OST) has expired. The OST is used after waking up from Sleep and after any type of Reset. The OST is not used with the EC or RC Clock modes so that the FSCM will be active as soon as the Reset or wake-up has completed. When the FSCM is enabled, the Two-Speed Start-up is also enabled. Therefore, the device will always be executing code while the OST is operating.

Note:	Due to the wide range of oscillator start-up times, the Fail-Safe circuit is not active during oscillator start-up (i.e., after exiting Reset or Sleep). After an appropriate amount of time, the user should check the Status bits in the OSCSTAT register to verify the oscillator start-up and that the system clock switchover has successfully completed.

12.1 Alternate Pin Function

The Alternate Pin Function Control (APFCON) registers are used to steer specific peripheral input and output functions between different pins. The APFCON registers are shown in Register 12-1. For this device family, the following functions can be moved between different pins.

- $\overline{SS}$ (Slave Select)
- CCP2

These bits have no effect on the values of any TRIS register. PORT and TRIS overrides will be routed to the correct pin. The unselected pin will be unaffected.

REGISTER 12-1: APFCON: ALTERNATE PIN FUNCTION CONTROL REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0/0	R/W-0/0
—	—	—	—	—	—	SSSEL	CCP2SEL
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-2 **Unimplemented:** Read as ‘0’

bit 1 **SSSEL:** Pin Selection bit
- 0 = $\overline{SS}$ function is on RA5
- 1 = $\overline{SS}$ function is on RA0

bit 0 **CCP2SEL:** Pin Selection bit
- 0 = CCP2 function is on RC1
- 1 = CCP2 function is on RB3

14.3 Register Definitions: FVR Control

REGISTER 14-1: FVRCON: FIXED VOLTAGE REFERENCE CONTROL REGISTER

R/W-0/0	R-q/q	R/W-0/0	R/W-0/0	U-0	U-0	R/W-0/0	R/W-0/0
FVREN(1)	FVRRDY(2)	TSEN(3)	TSRNG(3)	—	—	ADFVR<1:0>(1)	
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	q = Value depends on condition

bit 7 **FVREN:** Fixed Voltage Reference Enable bit(1)
0 = Fixed Voltage Reference is disabled
1 = Fixed Voltage Reference is enabled

bit 6 **FVRRDY:** Fixed Voltage Reference Ready Flag bit(2)
0 = Fixed Voltage Reference output is not ready or not enabled
1 = Fixed Voltage Reference output is ready for use

bit 5 **TSEN:** Temperature Indicator Enable bit(3)
0 = Temperature Indicator is disabled
1 = Temperature Indicator is enabled

bit 4 **TSRNG:** Temperature Indicator Range Selection bit(3)
0 = $V_{OUT} = V_{DD} - 2V_T$ (Low Range)
1 = $V_{OUT} = V_{DD} - 4V_T$ (High Range)

bit 3-2 **Unimplemented:** Read as '0'

bit 1-0 **ADFVR<1:0>:** ADC FVR Buffer Gain Selection bits(1)
11 = ADC FVR Buffer Gain is 4x, with output $V_{ADFVR} = 4x\ V_{FVR}$(4)
10 = ADC FVR Buffer Gain is 2x, with output $V_{ADFVR} = 2x\ V_{FVR}$(4)
01 = ADC FVR Buffer Gain is 1x, with output $V_{ADFVR} = 1x\ V_{FVR}$
00 = ADC FVR Buffer is off

Note 1: To minimize current consumption when the FVR is disabled, the FVR buffers should be turned off by clearing the Buffer Gain Selection bits.
2: FVRRDY is always '1' on PIC16F1516/7/8/9 only.
3: See **Section 15.0 "Temperature Indicator Module"** for additional information.
4: Fixed Voltage Reference output cannot exceed V_{DD}.

TABLE 14-2: SUMMARY OF REGISTERS ASSOCIATED WITH FIXED VOLTAGE REFERENCE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on page
FVRCON	FVREN	FVRRDY	TSEN	TSRNG	—	—	ADFVR<1:0>		128

Legend: Shaded cells are unused by the Fixed Voltage Reference module.

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The I²C interface supports the following modes and features:

- Master mode
- Slave mode
- Byte NACKing (Slave mode)
- Limited Multi-master support
- 7-bit and 10-bit addressing
- Start and Stop interrupts
- Interrupt masking
- Clock stretching
- Bus collision detection
- General call address matching
- Address masking
- Address Hold and Data Hold modes
- Selectable SDA hold times

Figure 21-2 is a block diagram of the I²C interface module in Master mode. Figure 21-3 is a diagram of the I²C interface module in Slave mode.

FIGURE 21-2: MSSP BLOCK DIAGRAM (I²C MASTER MODE)

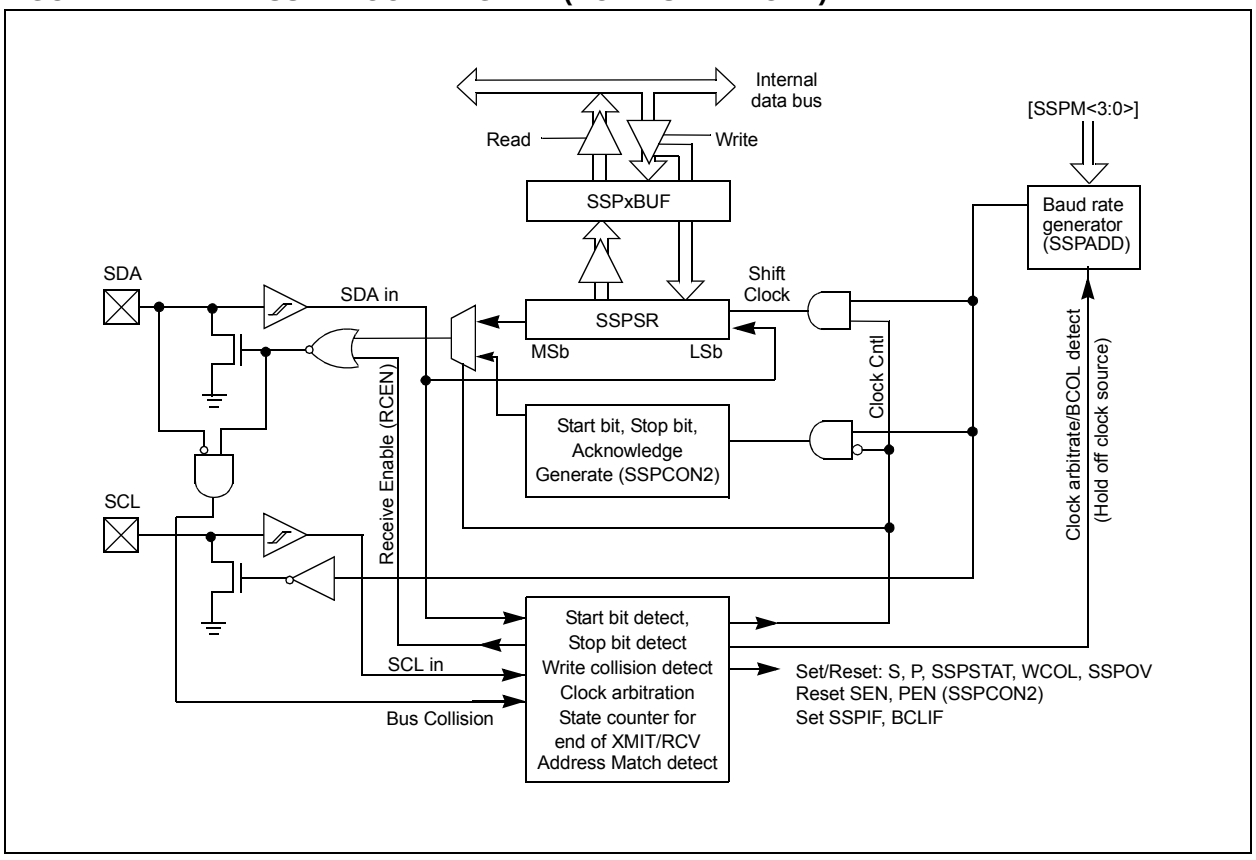

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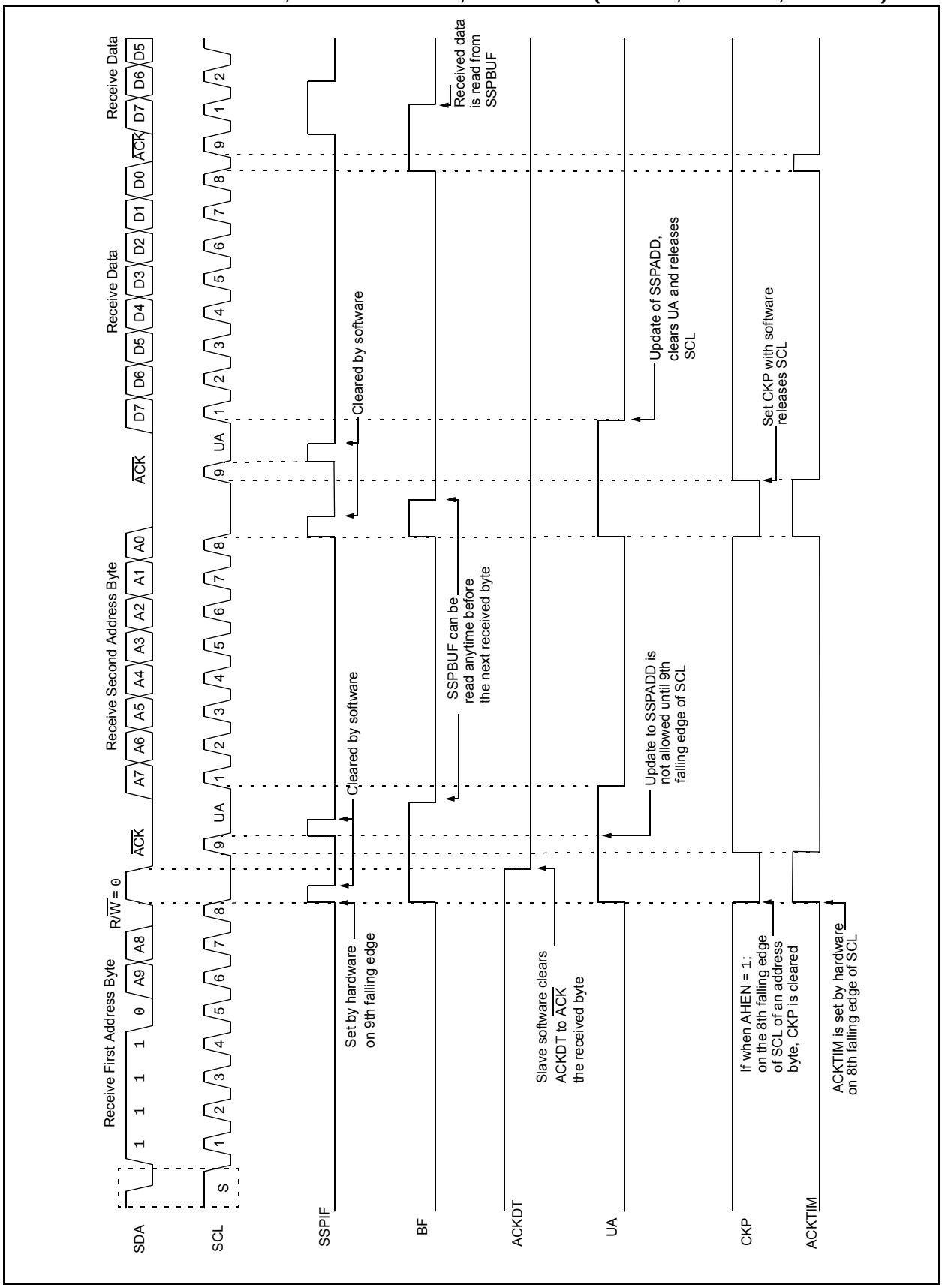
FIGURE 21-21: I²C SLAVE, 10-BIT ADDRESS, RECEPTION (SEN = 0, AHEN = 1, DHEN = 0)



21.6.4 I²C MASTER MODE START CONDITION TIMING

To initiate a Start condition (Figure 21-26), the user sets the Start Enable bit, SEN bit of the SSPCON2 register. If the SDA and SCL pins are sampled high, the Baud Rate Generator is reloaded with the contents of SSPADD<7:0> and starts its count. If SCL and SDA are both sampled high when the Baud Rate Generator times out (TBRG), the SDA pin is driven low. The action of the SDA being driven low while SCL is high is the Start condition and causes the S bit of the SSPSTAT register to be set. Following this, the Baud Rate Generator is reloaded with the contents of SSPADD<7:0> and resumes its count. When the Baud Rate Generator times out (TBRG), the SEN bit of the SSPCON2 register will be automatically cleared by hardware; the Baud Rate Generator is suspended, leaving the SDA line held low and the Start condition is complete.

Note 1: If at the beginning of the Start condition, the SDA and SCL pins are already sampled low, or if during the Start condition, the SCL line is sampled low before the SDA line is driven low, a bus collision occurs, the Bus Collision Interrupt Flag, BCLIF, is set, the Start condition is aborted and the I²C module is reset into its Idle state.

2: The Philips I²C Specification states that a bus collision cannot occur on a Start.

FIGURE 21-26: FIRST START BIT TIMING

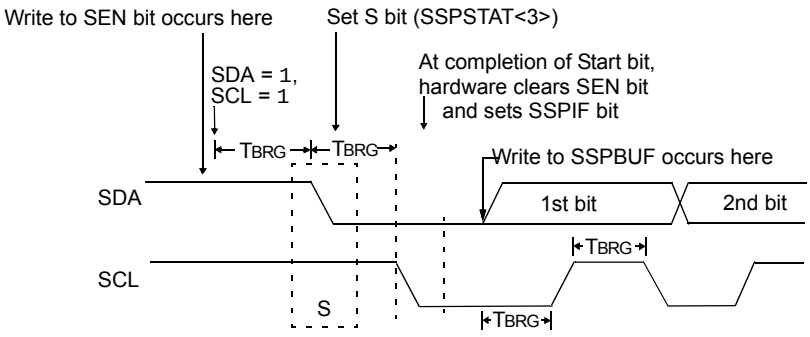


TABLE 22-4: BAUD RATES FOR ASYNCHRONOUS MODES (CONTINUED)

BAUD RATE	SYNC = 0, BRGH = 1, BRG16 = 1 or SYNC = 1, BRG16 = 1											
	FOSC = 20.000 MHz			FOSC = 18.432 MHz			FOSC = 16.000 MHz			FOSC = 11.0592 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	300.0	0.00	16665	300.0	0.00	15359	300.0	0.00	13332	300.0	0.00	9215
1200	1200	-0.01	4166	1200	0.00	3839	1200.1	0.01	3332	1200	0.00	2303
2400	2400	0.02	2082	2400	0.00	1919	2399.5	-0.02	1666	2400	0.00	1151
9600	9597	-0.03	520	9600	0.00	479	9592	-0.08	416	9600	0.00	287
10417	10417	0.00	479	10425	0.08	441	10417	0.00	383	10433	0.16	264
19.2k	19.23k	0.16	259	19.20k	0.00	239	19.23k	0.16	207	19.20k	0.00	143
57.6k	57.47k	-0.22	86	57.60k	0.00	79	57.97k	0.64	68	57.60k	0.00	47
115.2k	116.3k	0.94	42	115.2k	0.00	39	114.29k	-0.79	34	115.2k	0.00	23

BAUD RATE	SYNC = 0, BRGH = 1, BRG16 = 1 or SYNC = 1, BRG16 = 1											
	FOSC = 8.000 MHz			FOSC = 4.000 MHz			FOSC = 3.6864 MHz			FOSC = 1.000 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	300.0	0.00	6666	300.0	0.01	3332	300.0	0.00	3071	300.1	0.04	832
1200	1200	-0.02	1666	1200	0.04	832	1200	0.00	767	1202	0.16	207
2400	2401	0.04	832	2398	0.08	416	2400	0.00	383	2404	0.16	103
9600	9615	0.16	207	9615	0.16	103	9600	0.00	95	9615	0.16	25
10417	10417	0	191	10417	0.00	95	10473	0.53	87	10417	0.00	23
19.2k	19.23k	0.16	103	19.23k	0.16	51	19.20k	0.00	47	19.23k	0.16	12
57.6k	57.14k	-0.79	34	58.82k	2.12	16	57.60k	0.00	15	—	—	—
115.2k	117.6k	2.12	16	111.1k	-3.55	8	115.2k	0.00	7	—	—	—

22.6 EUSART Operation During Sleep

The EUSART will remain active during Sleep only in the Synchronous Slave mode. All other modes require the system clock and therefore cannot generate the necessary signals to run the Transmit or Receive Shift registers during Sleep.

Synchronous Slave mode uses an externally generated clock to run the Transmit and Receive Shift registers.

22.6.1 SYNCHRONOUS RECEIVE DURING SLEEP

To receive during Sleep, all the following conditions must be met before entering Sleep mode:

- RCSTA and TXSTA Control registers must be configured for Synchronous Slave Reception (see **Section 22.5.2.4 "Synchronous Slave Reception Setup:"**).
- If interrupts are desired, set the RCIE bit of the PIE1 register and the GIE and PEIE bits of the INTCON register.
- The RCIF interrupt flag must be cleared by reading RCREG to unload any pending characters in the receive buffer.

Upon entering Sleep mode, the device will be ready to accept data and clocks on the RX/DT and TX/CK pins, respectively. When the data word has been completely clocked in by the external device, the RCIF interrupt flag bit of the PIR1 register will be set. Thereby, waking the processor from Sleep.

Upon waking from Sleep, the instruction following the SLEEP instruction will be executed. If the Global Interrupt Enable (GIE) bit of the INTCON register is also set, then the Interrupt Service Routine at address 004h will be called.

22.6.2 SYNCHRONOUS TRANSMIT DURING SLEEP

To transmit during Sleep, all the following conditions must be met before entering Sleep mode:

- RCSTA and TXSTA Control registers must be configured for synchronous slave transmission (see **Section 22.5.2.2 "Synchronous Slave Transmission Setup:"**).
- The TXIF interrupt flag must be cleared by writing the output data to the TXREG, thereby filling the TSR and transmit buffer.
- If interrupts are desired, set the TXIE bit of the PIE1 register and the PEIE bit of the INTCON register.
- Interrupt enable bits TXIE of the PIE1 register and PEIE of the INTCON register must set.

Upon entering Sleep mode, the device will be ready to accept clocks on TX/CK pin and transmit data on the RX/DT pin. When the data word in the TSR has been completely clocked out by the external device, the pending byte in the TXREG will transfer to the TSR and the TXIF flag will be set. Thereby, waking the processor from Sleep. At this point, the TXREG is available to accept another character for transmission, which will clear the TXIF flag.

Upon waking from Sleep, the instruction following the SLEEP instruction will be executed. If the Global Interrupt Enable (GIE) bit is also set then the Interrupt Service Routine at address 0004h will be called.

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DECFSZ **Decrement f, Skip if 0**

Syntax:	[*label*] DECFSZ f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(f) - 1 → (destination); skip if result = 0
Status Affected:	None
Description:	The contents of register 'f' are decremented. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed back in register 'f'. If the result is '1', the next instruction is executed. If the result is '0', then a NOP is executed instead, making it a 2-cycle instruction.

GOTO **Unconditional Branch**

Syntax:	[*label*] GOTO k
Operands:	$0 \le k \le 2047$
Operation:	k → PC<10:0> PCLATH<6:3> → PC<14:11>
Status Affected:	None
Description:	GOTO is an unconditional branch. The 11-bit immediate value is loaded into PC bits <10:0>. The upper bits of PC are loaded from PCLATH<4:3>. GOTO is a 2-cycle instruction.

INCF **Increment f**

Syntax:	[*label*] INCF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(f) + 1 → (destination)
Status Affected:	Z
Description:	The contents of register 'f' are incremented. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed back in register 'f'.

INCFSZ **Increment f, Skip if 0**

Syntax:	[*label*] INCFSZ f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(f) + 1 → (destination), skip if result = 0
Status Affected:	None
Description:	The contents of register 'f' are incremented. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed back in register 'f'. If the result is '1', the next instruction is executed. If the result is '0', a NOP is executed instead, making it a 2-cycle instruction.

IORLW **Inclusive OR literal with W**

Syntax:	[*label*] IORLW k
Operands:	$0 \le k \le 255$
Operation:	(W) .OR. k → (W)
Status Affected:	Z
Description:	The contents of the W register are OR'ed with the 8-bit literal 'k'. The result is placed in the W register.

IORWF **Inclusive OR W with f**

Syntax:	[*label*] IORWF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(W) .OR. (f) → (destination)
Status Affected:	Z
Description:	Inclusive OR the W register with register 'f'. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed back in register 'f'.

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RETFIE **Return from Interrupt**

Syntax: [*label*] RETFIE

Operands: None

Operation: TOS → PC,
1 → GIE

Status Affected: None

Description: Return from Interrupt. Stack is POPed and Top-of-Stack (TOS) is loaded in the PC. Interrupts are enabled by setting Global Interrupt Enable bit, GIE (INTCON<7>). This is a 2-cycle instruction.

Words: 1

Cycles: 2

Example:

```
RETFIE
```

After Interrupt
PC = TOS
GIE = 1

RETLW **Return with literal in W**

Syntax: [*label*] RETLW k

Operands: 0 ≤ k ≤ 255

Operation: k → (W);
TOS → PC

Status Affected: None

Description: The W register is loaded with the eight bit literal 'k'. The program counter is loaded from the top of the stack (the return address). This is a 2-cycle instruction.

Words: 1

Cycles: 2

Example:

```
CALL TABLE;W contains table
    ;offset value
•   ;W now has table value
•
•
ADDWF PC  ;W = offset
RETLW k1  ;Begin table
RETLW k2  ;
•
•
•
RETLW kn  ; End of table
```

Before Instruction
W = 0x07
After Instruction
W = value of k8

RETURN **Return from Subroutine**

Syntax: [*label*] RETURN

Operands: None

Operation: TOS → PC

Status Affected: None

Description: Return from subroutine. The stack is POPed and the top of the stack (TOS) is loaded into the program counter. This is a 2-cycle instruction.

RLF **Rotate Left f through Carry**

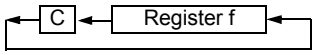
Syntax: [*label*] RLF f,d

Operands: 0 ≤ f ≤ 127
d ∈ [0,1]

Operation: See description below

Status Affected: C

Description: The contents of register 'f' are rotated one bit to the left through the Carry flag. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is stored back in register 'f'.



Words: 1

Cycles: 1

Example:

```
RLF     REG1,0
```

Before Instruction
REG1 = 1110 0110
C = 0
After Instruction
REG1 = 1110 0110
W = 1100 1100
C = 1

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25.0 ELECTRICAL SPECIFICATIONS

25.1 Absolute Maximum Ratings(†)

Ambient temperature under bias ..... -40°C to +125°C

Storage temperature ..... -65°C to +150°C

Voltage on V_{DD} with respect to V_{SS}, PIC16F1516/7/8/9 ..... -0.3V to +6.5V

Voltage on V_{DD} with respect to V_{SS}, PIC16LF1516/7/8/9 ..... -0.3V to +4.0V

Voltage on $\overline{MCLR}$ with respect to Vss ..... -0.3V to +9.0V

Voltage on all other pins with respect to V_{SS} ..... -0.3V to (V_{DD} + 0.3V)

Total power dissipation(2) ..... 800 mW

Maximum current

on V_{SS} pin for 28-Pin devices(1)

-40°C ≤ T_A ≤ +85°C ..... 350 mA
+85°C ≤ T_A ≤ +125°C ..... 120 mA

on V_{DD} pin for 28-Pin devices(1)

-40°C ≤ T_A ≤ +85°C ..... 250 mA
+85°C ≤ T_A ≤ +125°C ..... 85 mA

on V_{SS} pin for 40/44-Pin devices(1)

-40°C ≤ T_A ≤ +85°C ..... 350 mA
+85°C ≤ T_A ≤ +125°C ..... 120 mA

on V_{DD} pin for 40/44-Pin devices(1)

-40°C ≤ T_A ≤ +85°C ..... 350 mA
+85°C ≤ T_A ≤ +125°C ..... 120 mA

Clamp current, I_K (V_{PIN} < 0 or V_{PIN} > V_{DD}) ..... ± 20 mA

Maximum output current sunk by any I/O pin ..... 50 mA

Maximum output current sourced by any I/O pin ..... 50 mA

Note 1: Maximum current rating requires even load distribution across I/O pins. Maximum current rating may be limited by the device package power dissipation characterizations, see Table 25-5 to calculate device specifications.

2: Power dissipation is calculated as follows: $P_{DIS} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum (V_{OI} \times I_{OL})$

† NOTICE: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure above maximum rating conditions for extended periods may affect device reliability.

25.5 DC Characteristics: Power-Down Currents (I_{PD})

PIC16LF1516/7/8/9			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended					
PIC16F1516/7/8/9			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended					
Param No.	Device Characteristics	Min.	Typ†	Max. +85°C	Max. +125°C	Units	Conditions	
							VDD	Note
	Power-down Currents (I_{PD})(2, 4)							
D022	Base IPD	—	0.02	1.0	8.0	µA	1.8	WDT, BOR, FVR, and SOSC disabled, all Peripherals Inactive
		—	0.03	2.0	9.0	µA	3.0	
D022	Base IPD	—	0.20	3.0	10	µA	2.3	WDT, BOR, FVR, and SOSC disabled, all Peripherals Inactive, Low-power regulator active
		—	0.30	4.0	12	µA	3.0	
		—	0.47	6.0	15	µA	5.0	
D023		—	0.50	6.0	14	µA	1.8	LPWDT Current **(Note 1)**
		—	0.80	7.0	17	µA	3.0	
D023		—	0.50	6.0	15	µA	2.3	LPWDT Current **(Note 1)**
		—	0.77	7.0	20	µA	3.0	
		—	0.85	8.0	22	µA	5.0	
D023A		—	8.5	23	25	µA	1.8	FVR current **(Note 1)**
		—	8.5	24	27	µA	3.0	
D023A		—	18	26	30	µA	2.3	FVR current **(Note 1)**
		—	19	27	37	µA	3.0	
		—	20	29	45	µA	5.0	
D024		—	8.0	17	20	µA	3.0	BOR Current **(Note 1)**
D024		—	8.0	17	30	µA	3.0	BOR Current **(Note 1)**
		—	9.0	20	40	µA	5.0	
D024A		—	0.30	4.0	8.0	µA	3.0	LPBOR Current
D024A		—	0.30	4.0	14	µA	3.0	LPBOR Current **(Note 1)**
		—	0.45	8.0	17	µA	5.0	
D025		—	0.3	5.0	9.0	µA	1.8	SOSC Current **(Note 1)**
		—	0.5	8.5	12	µA	3.0	
D025		—	1.1	6.0	10	µA	2.3	SOSC Current **(Note 1)**
		—	1.3	8.5	20	µA	3.0	
		—	1.4	10	25	µA	5.0	
D026		—	0.10	1.0	9.0	µA	1.8	ADC Current **(Note 1, 3)**, no conversion in progress
		—	0.10	2.0	10	µA	3.0	
D026		—	0.16	3.0	10	µA	2.3	ADC Current **(Note 1, 3)**, no conversion in progress
		—	0.40	4.0	11	µA	3.0	
		—	0.50	6.0	16	µA	5.0	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The peripheral Δ current can be determined by subtracting the base IPD current from this limit. Max values should be used when calculating total current consumption.

2: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD.

3: ADC clock source is FRC.

4: VREGPM = 1, PIC16F1516/7/8/9 only.

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FIGURE 26-1: IDD, LP OSCILLATOR MODE, FOSC = 32 kHz, PIC16LF1516/7/8/9 ONLY

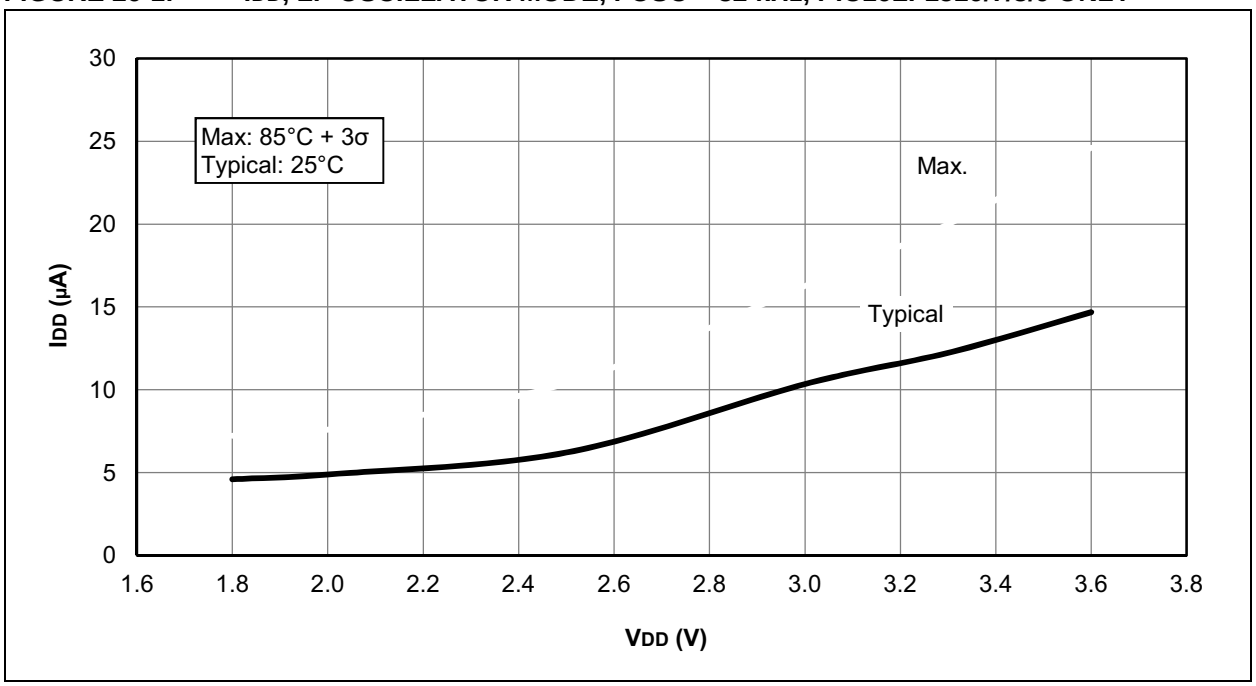

FIGURE 26-2: IDD, LP OSCILLATOR MODE, FOSC = 32 kHz, PIC16F1516/7/8/9 ONLY

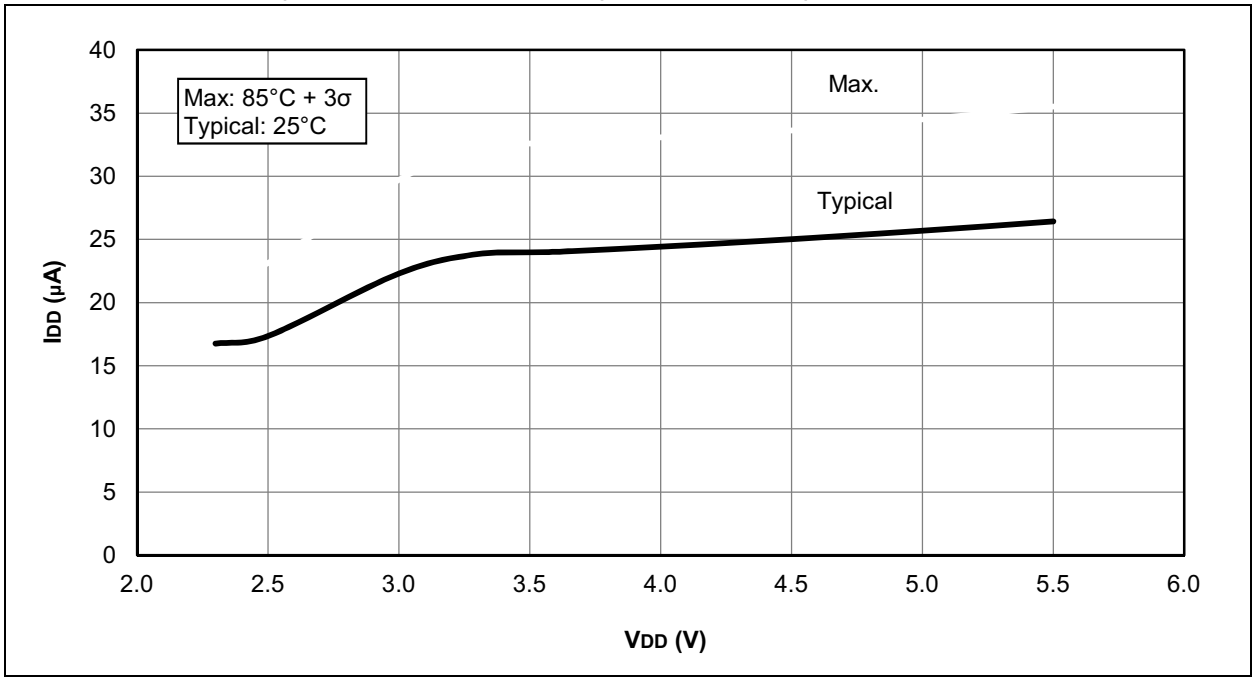

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FIGURE 26-17: IDD TYPICAL, EC OSCILLATOR, HIGH-POWER MODE, PIC16F1516/7/8/9 ONLY

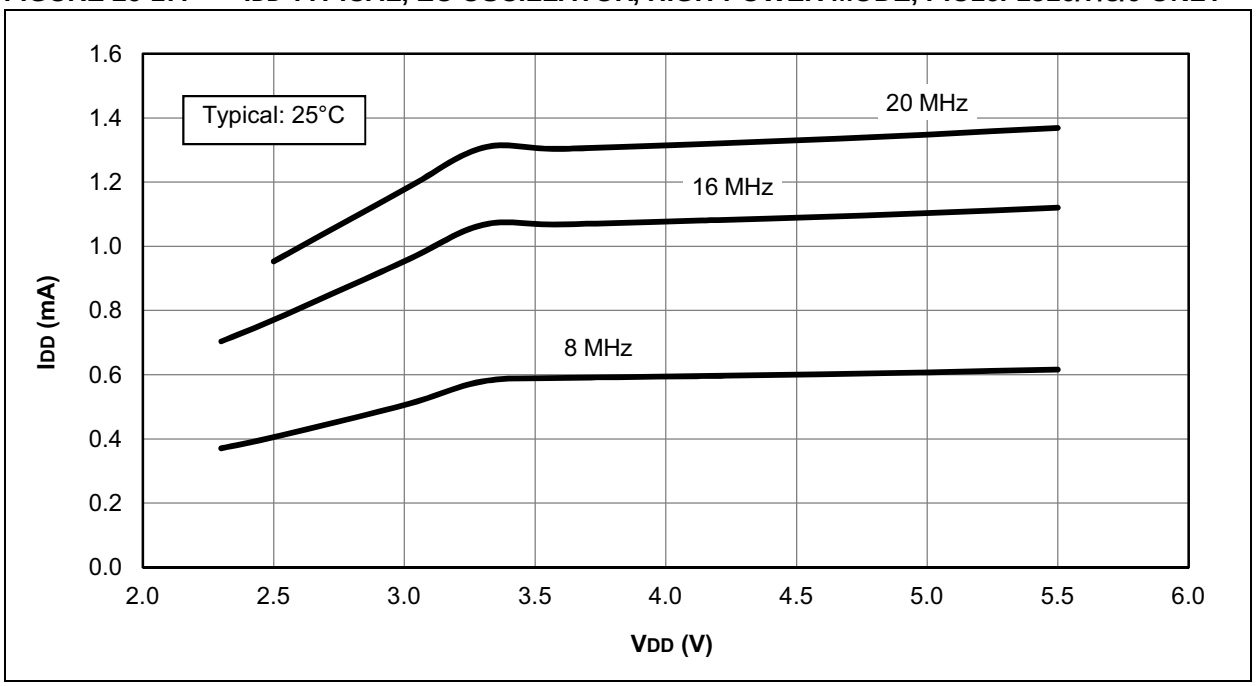

FIGURE 26-18: IDD MAXIMUM, EC OSCILLATOR, HIGH-POWER MODE, PIC16F1516/7/8/9 ONLY

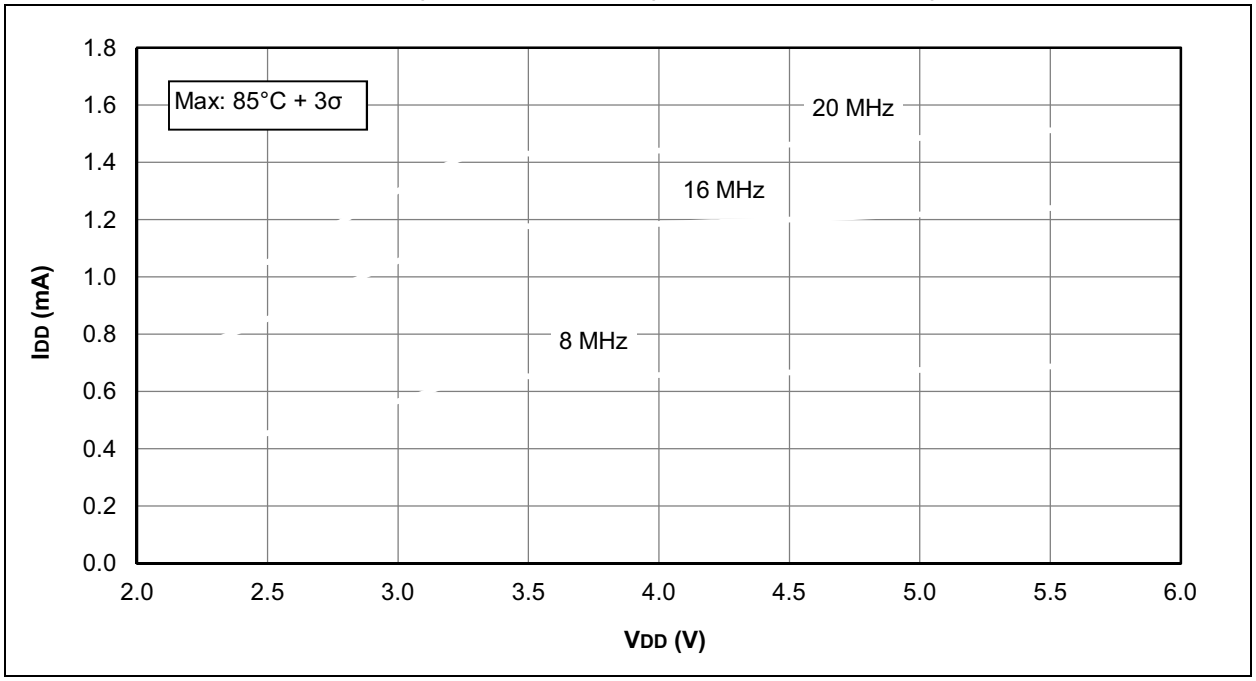

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FIGURE 26-25: IDD TYPICAL, HFINTOSC MODE, PIC16F1516/7/8/9 ONLY

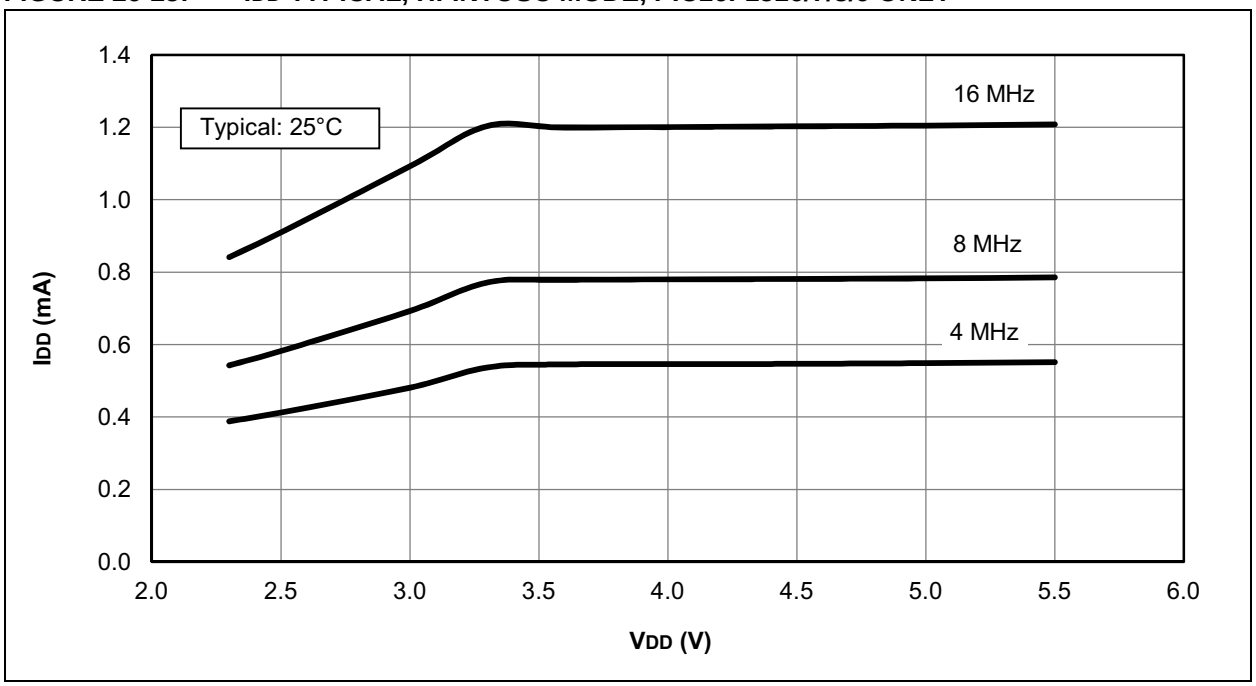
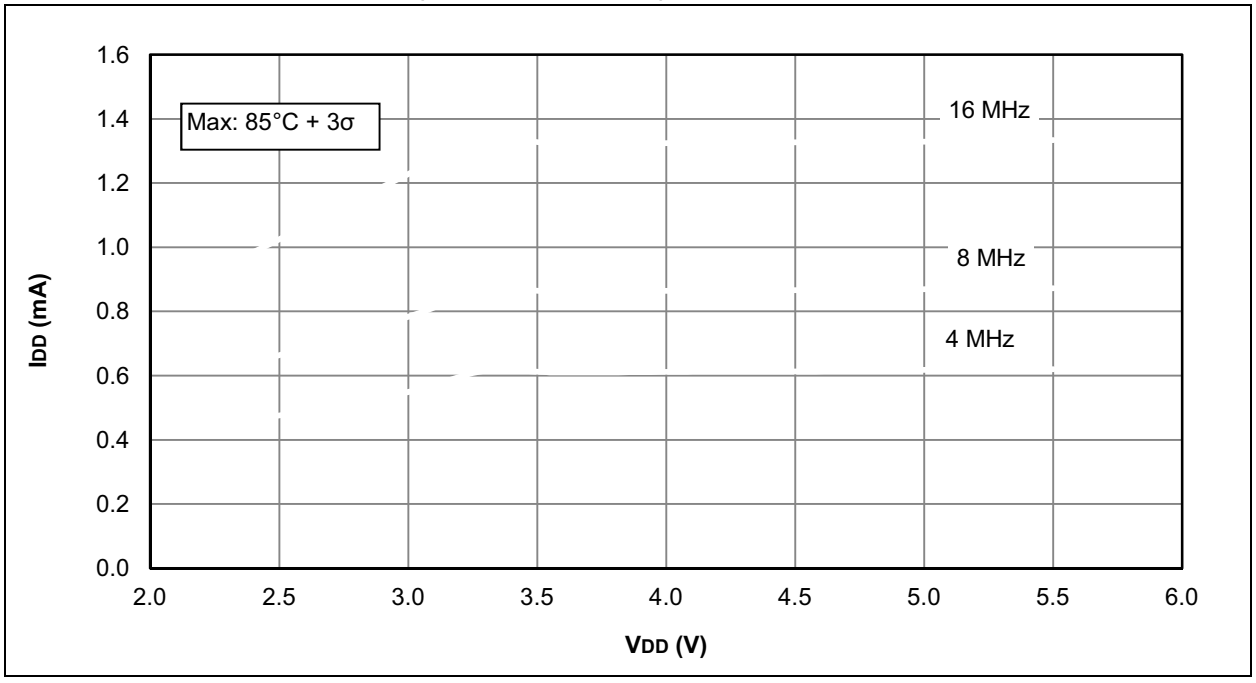


FIGURE 26-26: IDD MAXIMUM, HFINTOSC MODE, PIC16F1516/7/8/9 ONLY



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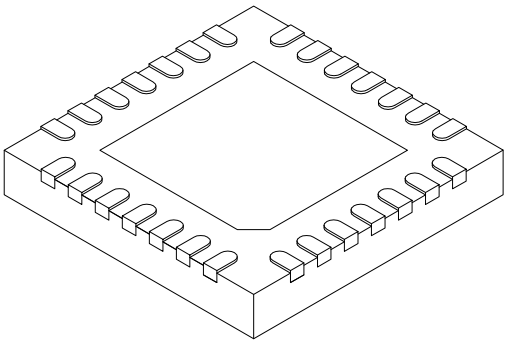
28-Lead Plastic Quad Flat, No Lead Package (ML) - 6x6 mm Body [QFN]
With 0.55 mm Terminal Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units	MILLIMETERS		
Dimension	Limits	MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		0.65 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	A3		0.20 REF	
Overall Width	E		6.00 BSC	
Exposed Pad Width	E2	3.65	3.70	4.20
Overall Length	D		6.00 BSC	
Exposed Pad Length	D2	3.65	3.70	4.20
Terminal Width	b	0.23	0.30	0.35
Terminal Length	L	0.50	0.55	0.70
Terminal-to-Exposed Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M.
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-105C Sheet 2 of 2

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PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	[X](1)	-	X	/XX	XXX
Device	Tape and Reel Option		Temperature Range	Package	Pattern

Device:	PIC16F1516, PIC16LF1516 PIC16F1517, PIC16LF1517 PIC16F1518, PIC16LF1518 PIC16F1519, PIC16LF1519	
Tape and Reel Option:	Blank T	= Standard packaging (tube or tray) = Tape and Reel(1)
Temperature Range:	I E	= -40°C to +85°C (Industrial) = -40°C to +125°C (Extended)
Package:(2)	ML MV P PT SO SP SS	= Thin Quad Flat, no lead (QFN) = Ultra Thin Quad Flat, no lead (UQFN) = Plastic DIP (PDIP) = TQFP = SOIC = Skinny Plastic DIP (SPDIP) = SSOP
Pattern:	QTP, SQTP, Code or Special Requirements (blank otherwise)	

Examples:

a) PIC16F1516T - I/MV 301
Tape and Reel,
Industrial temperature,
UQFN package,
QTP pattern #301

b) PIC16F1519 - I/P
Industrial temperature
PDIP package

c) PIC16F1518 - E/SS
Extended temperature,
SSOP package

Note 1: Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes and is not printed on the device package. Check with your Microchip Sales Office for package availability with the Tape and Reel option.

2: For other small form-factor package availability and marking information, please visit www.microchip.com/packaging or contact your local sales office.